

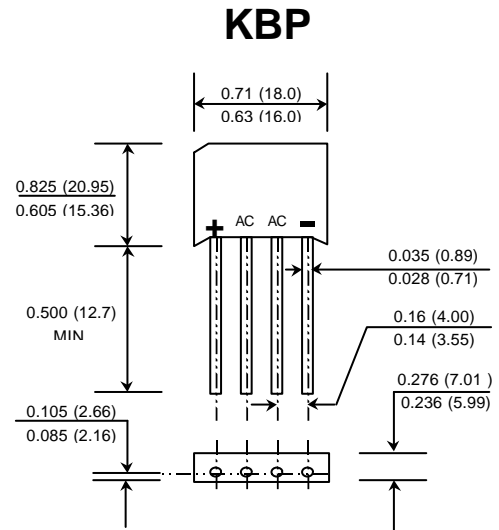
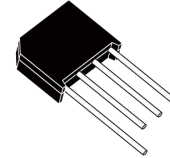
**VOLTAGE RANGE: 50 - 1000V**  
**CURRENT: 2.0 A**

### Features

- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- UL Recognized File # E157705

### Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.7 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



Dimensions in inches and ( millimeter )

### Maximum Ratings and Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	KBP 200	KBP 201	KBP 202	KBP 204	KBP 206	KBP 208	KBP 210	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>								
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V <sub>R</sub>								
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)	I <sub>O</sub>	2.0							A
@T <sub>A</sub> = 50°C									
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	60							A
Forward Voltage (per element)	V <sub>FM</sub>	1.1							V
@I <sub>F</sub> = 2.0A									
Peak Reverse Current	I <sub>RM</sub>	10							μA
@T <sub>A</sub> = 25°C									
At Rated DC Blocking Voltage		500							
@T <sub>A</sub> = 100°C									
Rating for Fusing (t<8.3ms)	I <sup>2</sup> <sub>t</sub>	15							A <sup>2</sup> s
Typical Junction Capacitance per element (Note 2)	C <sub>j</sub>	25							pF
Typical Thermal Resistance (Note 3)	R <sub>θJA</sub>	30							K/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +165							°C

Note: 1. Leads maintained at ambient temperature at a distance of 9.5mm from the case.  
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.  
 3. Thermal resistance junction to ambient mounted on PC board with 12mm<sup>2</sup> copper pad.



### RATING AND CHARACTERISTIC CURVES ( KBP200 - KBP210 )

FIG.1 - DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

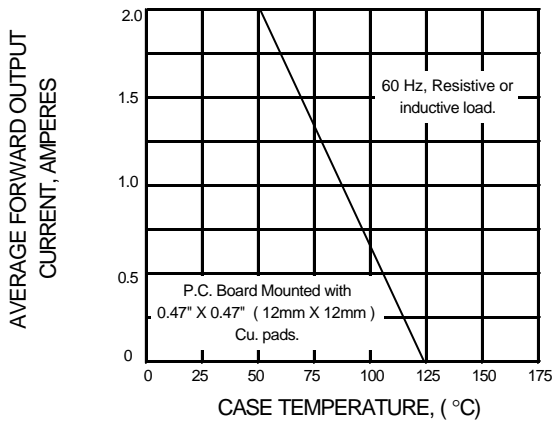


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

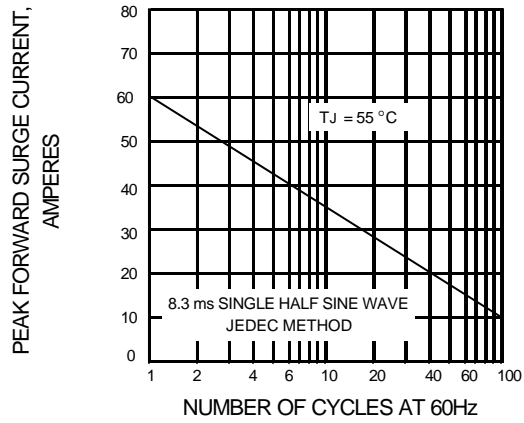


FIG.3 - TYPICAL FORWARD CHARACTERISTICS PER DIODE

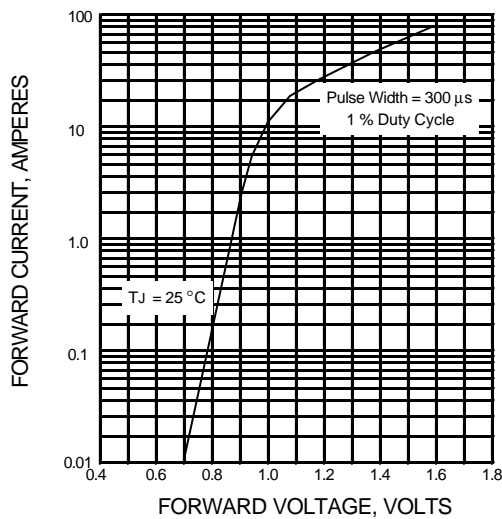


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

